

ABSTRACT OF THE DISCLOSURE

The invention provides an integrated device with corrosion-resistant capped bond pads. The capped bond pads include at least one aluminum bond pad on a semiconductor substrate. A layer of electroless nickel is disposed on the aluminum bond pad. A layer of electroless palladium is disposed on the electroless nickel, and a layer of immersion gold is disposed on the electroless palladium. A capped bond pad and a method of forming the capped bond pads are also disclosed.

10